



P-Channel Enhancement-Mode Lateral MOSFET

Ordering Information

| BV _{DSS} / BV _{DGS} | R _{DS(ON)} (max) | I _{D(ON)} (min) | V _{GS(th)} (max) | Order Number / Package | | |
|---------------------------------------|---------------------------|--------------------------|---------------------------|------------------------|----------|----------|
| | | | | TO-92 | SO-8 | Die |
| -16.5V | 1.5Ω | -1.25A | -1.0V | LP0701N3 | LP0701LG | LP0701ND |

Features

- Ultra low threshold
- High input impedance
- Low input capacitance
- Fast switching speeds
- Low on resistance
- Freedom from secondary breakdown
- Low input and output leakage
- Complementary N- and P-channel devices

Applications

- Logic level interfaces
- Solid state relays
- Battery operated systems
- Photo voltaic drives
- Analog switches
- General purpose line drivers

Absolute Maximum Ratings

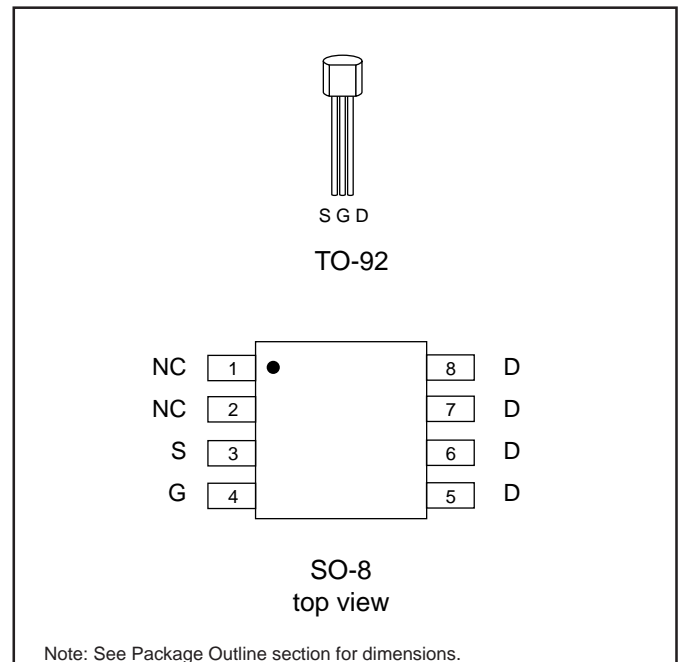
| | |
|-----------------------------------|-------------------|
| Drain-to-Source Voltage | BV _{DSS} |
| Drain-to-Gate Voltage | BV _{DGS} |
| Gate-to-Source Voltage | ± 10V |
| Operating and Storage Temperature | -55°C to +150°C |
| Soldering Temperature* | 300°C |

*Distance of 1.6 mm from case for 10 seconds.

Advanced MOS Technology

These enhancement-mode (normally-off) transistors utilize a lateral MOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and negative temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown. The low threshold voltage and low on-resistance characteristics are ideally suited for hand held battery operated applications.

Package Options



Thermal Characteristics

| Package | I_D (continuous)* | I_D (pulsed)* | Power Dissipation @ $T_c = 25^\circ\text{C}$ | θ_{jc} $^\circ\text{C/W}$ | θ_{ja} $^\circ\text{C/W}$ | I_{DR} | I_{DRM}^* |
|---------|---------------------|-----------------|---|-------------------------------------|-------------------------------------|----------|-------------|
| TO-92 | -0.5A | -1.25A | 1W | 125 | 170 | -0.5A | -1.25A |
| SO-8 | -0.7A | -1.25A | 1.5W [†] | 83 | 104 [†] | -0.7A | -1.25A |

* I_D (continuous) is limited by max rated T_j .

† Mounted on FR4 board, 25mm x 25mm x 1.57mm.

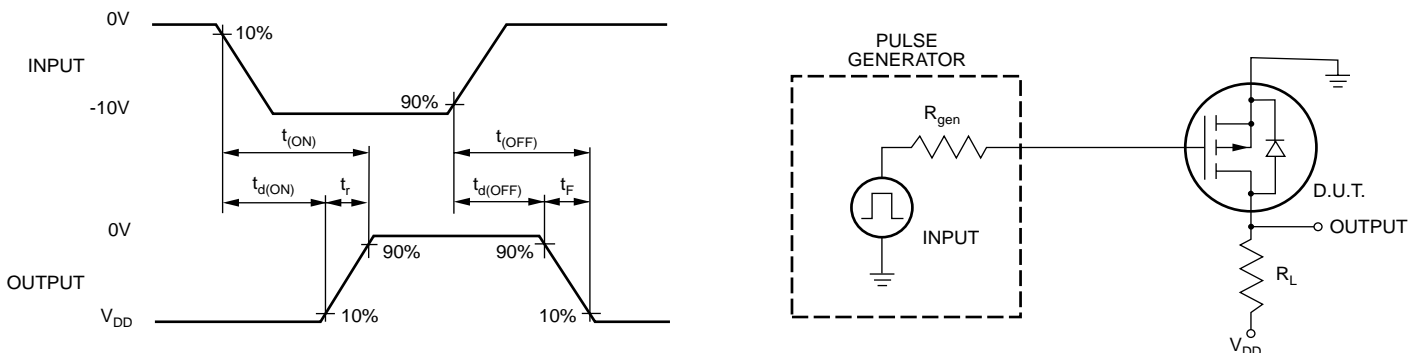
Electrical Characteristics (@ 25°C unless otherwise specified)

| Symbol | Parameter | Min | Typ | Max | Unit | Conditions |
|---------------------|--|-------|------|------|----------------------|--|
| BV_{DSS} | Drain-to-Source Breakdown Voltage | -16.5 | | | V | $V_{GS} = 0V, I_D = -1mA$ |
| $V_{GS(th)}$ | Gate Threshold Voltage | -0.5 | -0.7 | -1.0 | V | $V_{GS} = V_{DS}, I_D = -1mA$ |
| $\Delta V_{GS(th)}$ | Change in $V_{GS(th)}$ with Temperature | | | -4.0 | mV/ $^\circ\text{C}$ | $V_{GS} = V_{DS}, I_D = -1mA$ |
| I_{GSS} | Gate Body Leakage | | | -100 | nA | $V_{GS} = \pm 10V, V_{DS} = 0V$ |
| I_{DSS} | Zero Gate Voltage Drain Current | | | -100 | nA | $V_{DS} = -15V, V_{GS} = 0V$ |
| | | | | -1.0 | mA | $V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V, T_A = 125^\circ\text{C}$ |
| $I_{D(ON)}$ | ON-State Drain Current | | -0.4 | | A | $V_{GS} = V_{DS} = -2V$ |
| | | -0.6 | -1.0 | | A | $V_{GS} = V_{DS} = -3V$ |
| | | -1.25 | -2.3 | | A | $V_{GS} = V_{DS} = -5V$ |
| $R_{DS(ON)}$ | Static Drain-to-Source ON-State Resistance | | 2.0 | 4.0 | Ω | $V_{GS} = -2V, I_D = -50mA$ |
| | | | 1.7 | 2.0 | Ω | $V_{GS} = -3V, I_D = -150mA$ |
| | | | 1.3 | 1.5 | Ω | $V_{GS} = -5V, I_D = -300mA$ |
| $\Delta R_{DS(ON)}$ | Change in $R_{DS(ON)}$ with temperature | | | 0.75 | %/ $^\circ\text{C}$ | $V_{GS} = -5V, I_D = -300mA$ |
| G_{FS} | Forward Transconductance | 500 | 700 | | m Ω | $V_{DS} = -15V, I_D = -1A$ |
| C_{ISS} | Input Capacitance | | 120 | 250 | pF | $V_{GS} = 0V, V_{DS} = -15V, f = 1MHz$ |
| C_{OSS} | Common Source Output Capacitance | | 100 | 125 | | |
| C_{RSS} | Reverse Transfer Capacitance | | 40 | 60 | | |
| $t_{d(ON)}$ | Turn-ON Delay Time | | | 20 | ns | $V_{DD} = -15V, I_D = -1.25A,$ $R_{GEN} = 25\Omega$ |
| t_r | Rise Time | | | 20 | | |
| $t_{d(OFF)}$ | Turn-OFF Delay Time | | | 30 | | |
| t_f | Fall Time | | | 30 | | |
| V_{SD} | Diode Forward Voltage Drop | | -1.2 | -1.5 | V | $V_{GS} = 0V, I_{SD} = -500mA$ |

Note 1: All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300 μ s pulse, 2% duty cycle.)

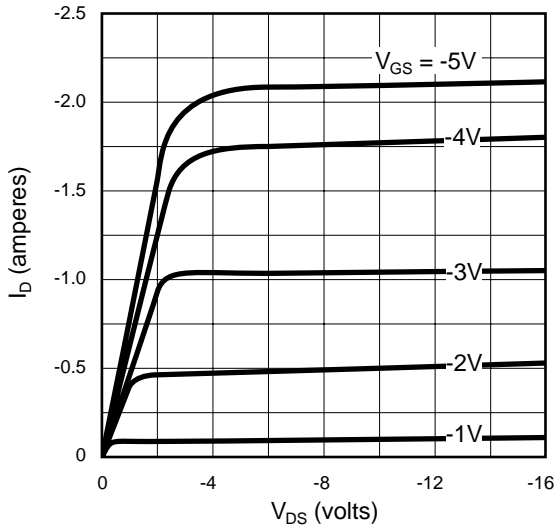
Note 2: All A.C. parameters sample tested.

Switching Waveforms and Test Circuit

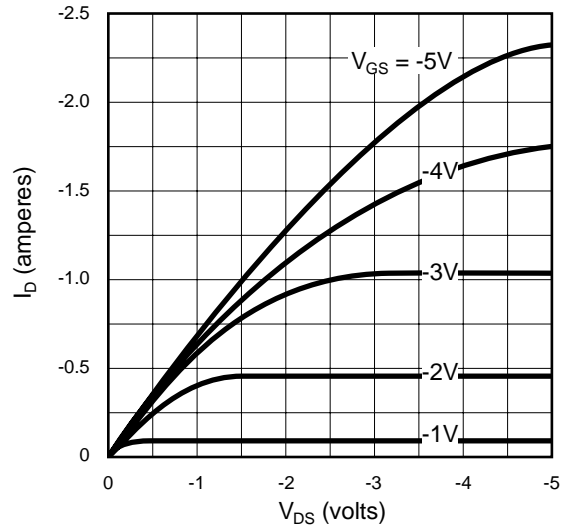


Typical Performance Curves

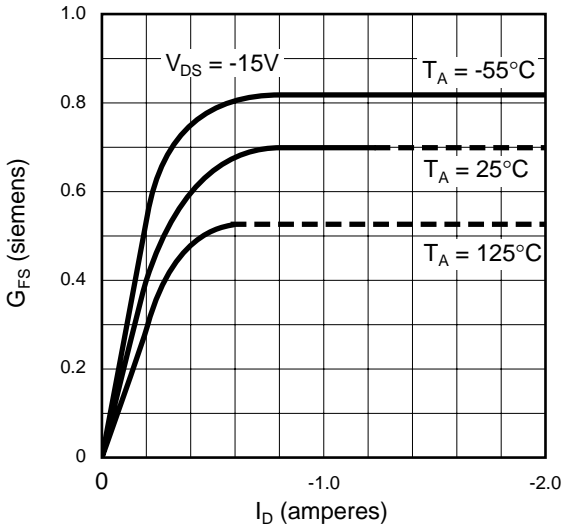
Output Characteristics



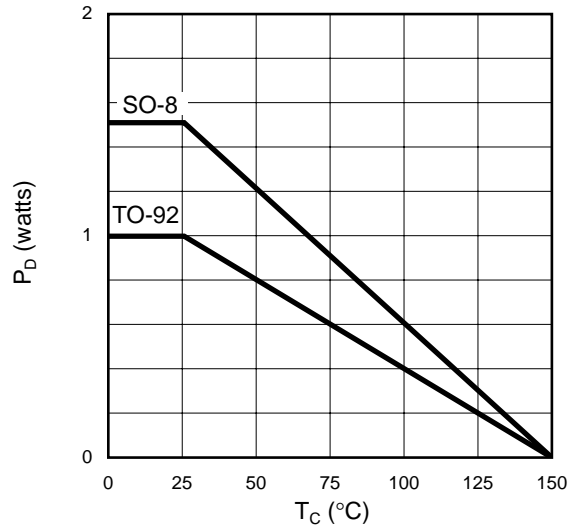
Saturation Characteristics



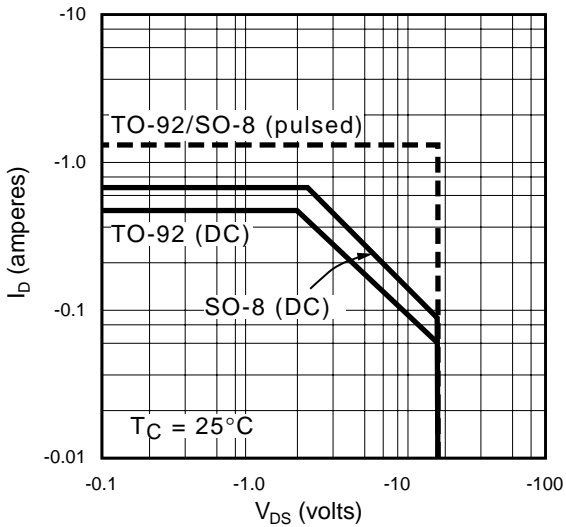
Transconductance vs. Drain Current



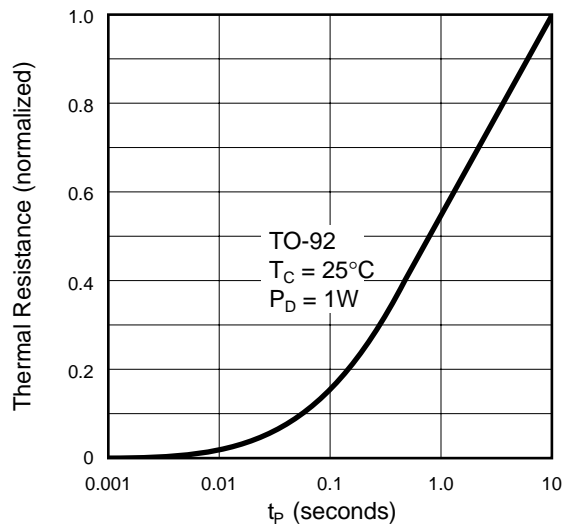
Power Dissipation vs. Case Temperature



Maximum Rated Safe Operating Area

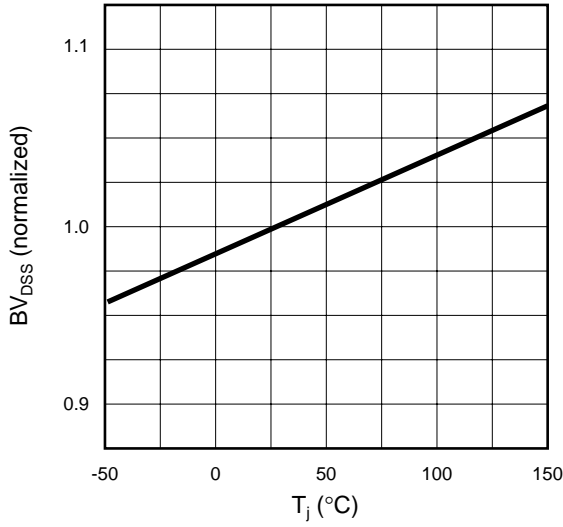


Thermal Response Characteristics

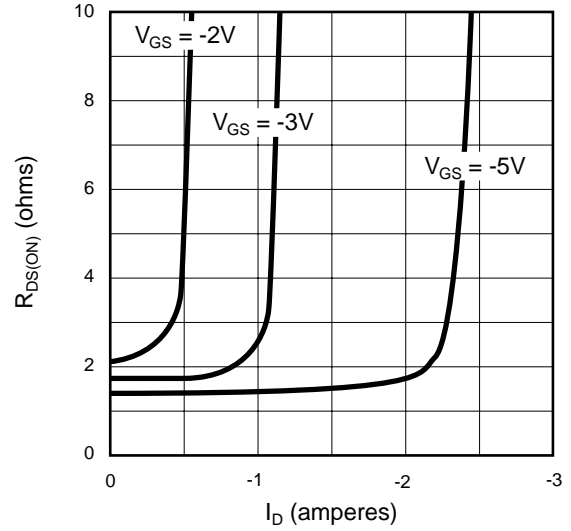


Typical Performance Curves

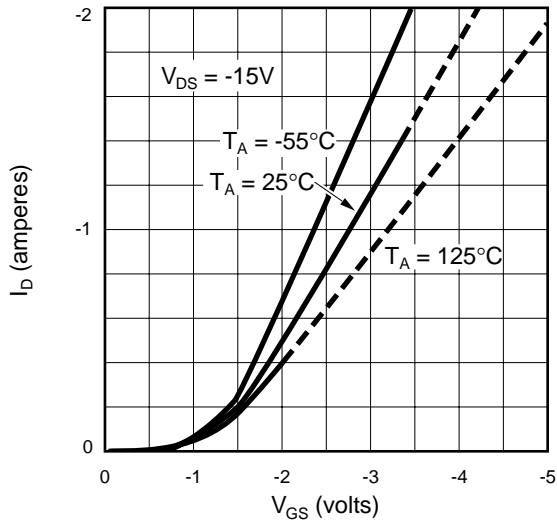
BV_{DSS} Variation with Temperature



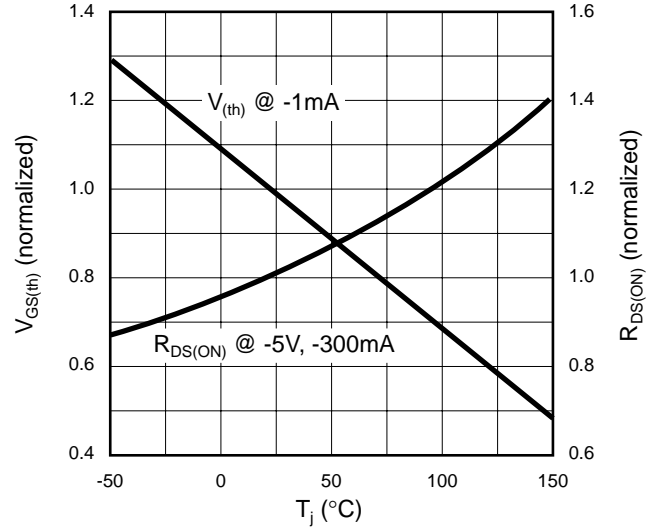
On-Resistance vs. Drain Current



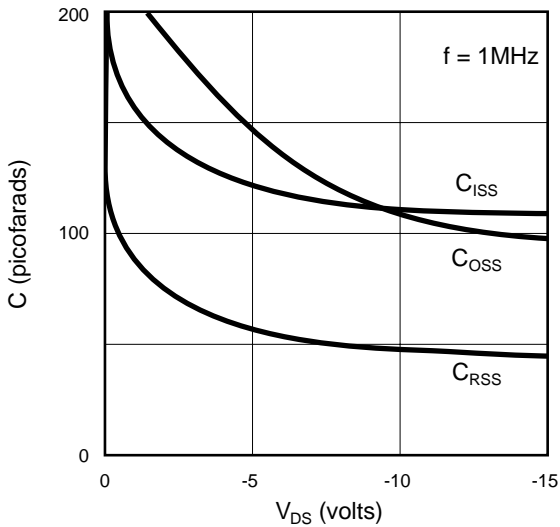
Transfer Characteristics



V_(th) and R_{DS} Variation with Temperature



Capacitance vs. Drain-to-Source Voltage



Gate Drive Dynamic Characteristics

